







# Call for Papers NordPac Conference June 10 – 12 2025 Copenhagen, Denmark Jointly arranged by: IMAPS Nordic

IEEE EPS Nordic

We are proud to announce that the NordPac 2025 conference will be held Copenhagen, Denmark. This is a perfect opportunity for you to present your revolutionary work within the field of microelectronic packaging while enjoying the normally beautiful weather in Copenhagen in June.

## Abstract submission

We hereby invite you to prepare an abstract for the conference. For NordPac 2025 we have expanded the possibilities for how you want to present you work. We will open three submission tracks:

- **Track 1** will require a **full paper submission** (4-6 pages). Accepted papers will be submitted for inclusion into IEEE Xplore subject to meeting IEEE Xplore's scope and quality requirements. (<u>http://ieeexplore.ieee.org/</u>).
- **Track 2** will only require an **extended abstract** (1-2 pages) and will only be published in the conference proceedings.
- **Track 3** is reserved for **commercial white papers** (1-4 pages) and will only be published in the conference proceedings. Presentations from all three tracks can appear in the same technical session.

The abstract submission deadline for all three tracks is January 31st, 2025.

Acceptance will be given within February 28<sup>th</sup>. After this, the three tracks follow different submission deadlines as indicated in the table below.

For full instructions on how to submit your paper and information on review process flow, please go to <u>www.nordpac.org</u>

### Summary of deadlines

Conference portal open for submission	October 2024
Abstract submission	January 31 <sup>st</sup> , 2025
Feedback on abstract	February 28 <sup>th</sup> , 2025
Track 1 – Full paper submission	April 30 <sup>th</sup> , 2025
Track 2 – Extended abstract submission	May 15 <sup>th</sup> , 2025
Track 3 – Commercial white paper submission	May 15 <sup>th</sup> , 2025
Notification of acceptance of all submissions	June 1 <sup>st</sup> , 2025

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## Topics

Proposed topics of microelectronics and packaging include:

Optoelectronics	Harsh environment Applications
Advanced Packaging	Electronics Reliability & Quality
Materials & Processes	Medical electronics
Power electronics	Wearable electronics
Green Technologies	Printed electronics
Advanced packaging for MEMS & sensors & sensor systems	

#### About the conference

The event brand NordPac was introduced in Gothenburg in 2017 as a collaboration between IMAPS Nordic and IEEE Electronics Packaging Society (EPS) Nordic. NordPac prides itself on being a small and specialised conference where networking is easy.

**Reviewed** papers will be submitted for publication in IEEE-Xplore with a licence to publish. The Licence allows the author to retain the copyright for the work and can publish it six months after the work has been published in IEEE-Xplore.

For the latest information about the conference and the exhibition, visit our homepage at <u>www.nordpac.org</u> or email to <u>info@nordpac.org</u>.



Main organiser



Technical co-sponsor



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